

PCN 13_0173 VALIDATION PLAN

The validation consists of

- a) Controlled experimental lot where 'extra active' is intentionally added within the bond pad area. These results will verify the effectiveness of the TGATE mask change at creating a robust and reliable bond pad structure.
- b) TGATE Modified Mask

Reference: attached PPT slides for explanation of proposed change.

#	Description	Success Criteria	Method	Sampling Plan	Schedule (Target)
1	E_Test Parameters	No change	E_Lot testing	100% of Wafers from Control Lot and TGATE Lot w' extra active.	July 31 st 2013
2	Probe	Increased yield on bond pad with TGATE oxide.	E_Testing of Control Lot vs TGATE lot w' extra active.	Electrical – 100% of die on both Control Lot and TGATE lot w' extra active.	August 30 th 2013
3	X Sections	Bond pad structures as anticipated.	FIB/SEM of bond pad structure vs control.	5 – taken from different locations.	August 30 th 2013
4	Bond Pull	No change	Bond Pull	100 wires / split	August 30 th 2013
5	Ball Shear	No change	Ball Shear	30 balls / split	August 30 th 2013